

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT6218054

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
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MASARU TAKAHAMA	04/22/2020
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Property Type	Number
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DATE SIGNED:	07/24/2020
Total Attachments: 2	
source=2020-06-18 Combined Declaration_Assignment (all named inventors) - SHIGA7.526AUS#page1.tif	
source=2020-06-18 Combined Declaration_Assignment (all named inventors) - SHIGA7.526AUS#page2.tif	

**COMBINED DECLARATION & ASSIGNMENT
UNDER 37 CFR 1.63(e)**

Attorney Reference No.: _____

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Title: SILICON ETCHING SOLUTION, SILICON ETCHING METHOD, AND METHOD OF PRODUCING SILICON FIN STRUCTURE

Legal Names of All Inventors: Ming-Yen CHUNG; and Masaru TAKAHAMA

Please Direct All Correspondence to Customer Number 20995

Declaration of Inventors

As an individual executing this Declaration, I hereby declare that:

This Declaration is directed to the invention identified above that: (check one)

Is attached, where "attached" means filed concurrently with.

Was filed on _____ as U.S. Application No. _____

Was filed on _____ as International Application No. _____

The above-identified application was made or authorized to be made by me.

I believe I am the original inventor or an original joint inventor of a claimed invention in the application.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

Assignment from Inventors

WHEREAS, the inventor(s) identified above (individual(s) hereinafter "ASSIGNOR") invented certain new and useful improvements, technology, inventions, developments, ideas or discoveries while under an obligation to assign related to the title identified above (collectively hereinafter referred to as the "Work") for which the application identified above has been or will be filed (hereinafter the "Application").

AND WHEREAS, TOKYO CHKA KOGYO CO., LTD. with its principal place of business at 150, Nakamaruko, Nakahara-ku, Kawasaki-shi, Kanagawa 211-0012 Japan (hereinafter the "ASSIGNEE"), desires to acquire the entire right, title, and interest in and to the Application and the Work.

NOW, THEREFORE, for good and valuable consideration of which receipt is hereby acknowledged, ASSIGNOR hereby acknowledges that ASSIGNOR has sold, assigned, transferred and set over, and by these presents does hereby sell, assign, transfer and set over, unto said ASSIGNEE, its successors, legal representatives and assigns, the entire right, title, and interest throughout the world in the Application and the Work, including all patent properties filed or issued upon the Application and the Work; where "Patent Properties" include, but are not limited to:

all provisional applications relating thereto (including but not limited to U.S. Provisional Application No(s). _____ filed _____ (respectively if plural applications));

all nonprovisional applications claiming priority to aforementioned provisional(s) and/or the present Application, including, all divisions, continuations, continuations-in-part, and reissues, and all Letters Patent of the United States which may be granted thereon and all reissues and extensions thereof; and

all rights of priority under International Conventions and any related Letters Patent which may hereafter be granted or filed in any country or countries foreign to the United States, all extensions, renewals and reissues thereof.

ASSIGNOR hereby acknowledges the ASSIGNEE as the Applicant for all aforementioned patent properties, and authorizes and requests the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications as

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Attorney Reference No.: _____

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Legal Names of All Inventors: Ming-Yen CHUNG and Masaru TAKAHAMA

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aforesaid, to issue all related Letters Patent to the ASSIGNEE, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND ASSIGNOR DOES HEREBY sell, assign, transfer, and convey to ASSIGNEE, its successors, legal representatives, and assigns all claims for damages and all remedies arising out of any violation of the rights assigned hereby that may have accrued prior to the date of assignment to ASSIGNEE, or may accrue hereafter, including, but not limited to, the right to sue for, collect, and retain damages for past infringements of said Letters Patent before or after issuance.

AND ASSIGNOR DOES HEREBY covenant and agree that ASSIGNOR will communicate to said ASSIGNEE, its successors, legal representatives and assigns, any facts known to ASSIGNOR respecting the Work, and testify in any legal proceeding, assist in the preparation of any other Patent Property relating to the Application and the Work or any improvements made thereto, sign/execute all lawful papers, and generally do everything possible to aid the ASSIGNEE, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for the Work in all countries.

1. Legal Name of Inventor: Ming-Yen CHUNG

Signature of Inventor: Ming Yen Chung Date: April 22, 2020

2. Legal Name of Inventor: Masaru TAKAHAMA

Signature of Inventor: Masaru Takahama Date: April 22, 2020